

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor(s) : Dusberg et al.  
Serial No. : 10/573,862  
Filed : October 24, 2006  
For : Heat-Conducting Packaging of Electronic Circuit Units  
Group Art Unit : 2815  
Confirmation No. : 7026  
Examiner : Chris C. Chu

Mail Stop: Amendments  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450


**STATEMENT UNDER 37 CFR 3.73(b)**

Infineon Technologies AG hereby states that it is the assignee of the entire right, title, and interest of the above-identified application. The assignment of the above-identified application from the Inventors to Infineon Technologies AG was recorded on June 7, 2006 and assigned Reel/Frame No. 017753/0136.

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

Respectfully submitted,

Dated: October 6, 2008

By:   
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